#### Supplier Name: Contact Info: Form/Declaration Type: Created on:

### Texas Instruments Inc. (DUNS# 00-732-1904) ti.com/support Distribute - RoHS and IEC 62474 DB

Distribute - RoHS and 05/30/2022

Details for "INA2134UA/2K5G4"

#### Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package   Pins	Package body size (mm)	Total device mass (mg)*
INA2134UA/2K5G4	NIPDAU	Level-3-260C-168 HR	TI MALAYSIA A/T	D   14	3.91X8.65X1.58	161.4

\*Total Device Mass

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

**Environmental Ratings Information** 

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

# **Component Information**

				Homogeneous Material Level		Component Level			
Component	Substance	CAS Number	Amount (mg)	Percentage %	ppm	Percentage %	ppm		
Bond Wire									
Other Nonferrous Metals and Alloys	Yttrium	7440-65-5	0.000001	0.000488	5	0.000001	0		
Precious Metals	Gold	7440-57-5	0.204889	99.998536	999985	0.126915	1269		
Precious Metals	Silver	7440-22-4	0.000002	0.000976	10	0.000001	0		
Sub-Total			0.204892	100	1000000	0.126917	1269		
Die Attach Adhesive									
Other Inorganic Materials	Silica	7631-86-9	0.026048	1.999974	20000	0.016135	161		
Precious Metals	Silver	7440-22-4	0.898668	69.000021	690000	0.556666	5567		
Thermoplastics	Epoxy	85954-11-6	0.377701	29.000005	290000	0.233961	2340		
Sub-Total			1.302417	100	1000000	0.806761	8068		
Lead Frame									
Copper and Its Alloys	Copper	7440-50-8	51.630205	99.865	998650	31.981509	319815		
Copper and Its Alloys	Iron	7439-89-6	0.0517	0.1	1000	0.032025	320		
Copper and Its Alloys	Phosphorus	7723-14-0	0.018095	0.035	350	0.011209	112		
Sub-Total			51.7	100	1000000	32.024743	320247		
Lead Frame Plating									
Nickel and Its Alloys	Nickel	7440-02-0	0.741936	95.12	951200	0.45958	4596		
Precious Metals	Gold	7440-57-5	0.006084	0.78	7800	0.003769	38		
Precious Metals	Palladium	7440-05-3	0.03198	4.1	41000	0.01981	198		
Sub-Total			0.78	100	1000000	0.483159	4832		
Mold Compound									
Other Inorganic Materials	Fused Silica	60676-86-0	88.741457	86	860000	54.969484	549695		
Other Plastics and Rubber	Carbon Black	1333-86-4	0.309563	0.3	3000	0.191754	1918		
Other Plastics and Rubber	Organic Phosphorus	1330-78-5	0.567533	0.55	5500	0.351549	3515		
Thermoplastics	Ероху	85954-11-6	13.569188	13.15	131500	8.405218	84052		
Sub-Total			103.187741	100	1000000	63.918005	639180		
Semiconductor Device									
Ceramics / Glass	Doped Silicon	7440-21-3	4.262625	100	1000000	2.640415	26404		
Sub-Total			4.262625	100	1000000	2.640415	26404		
Total			161.437675			100	1000000		

#### Important Note

The ppm calculations are at the homogeneous material level and are maximum concentration values. The ppm displayed represents the homogeneous material with the highest ppm

for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.

The ppm calculations are at the component level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the component. See Glossary of Terms for more details.

### Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSIs or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

## Product Content Methodology

For an explanation of the methods used to determine material weights, See Product Content Methodology

## Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

## Important Information/Disclaiment

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI" as is."

For additional information, please contact TI customer support.

## Signature: (click here for a fuller statement with a signed certificate)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality For further environmental statements, please go to www.ti.com/ecoinfo Created on: 05/30/2022

RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, II semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products are "Poi-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in http://www.ti.com/lit/pdf/szzq088

Green: Means the content of Chlorine (CI) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb203) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.